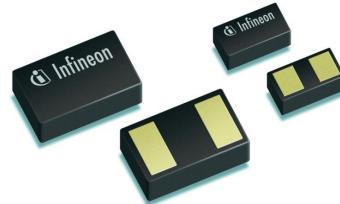


Bi-directional Low Capacitance TVS Diode

- ESD / transient protection of high-speed data lines in 3.3 / 5 / 12 V applications according to:
IEC61000-4-2 (ESD): ± 18 kV (air) ± 15 kV (contact)
IEC61000-4-4 (EFT): 40 A (5 / 50 ns)



- Extremely small form factor down to 0.62 x 0.32 x 0.31 mm³ (0201)
- Max. working voltage: -8 / +14 V
- Very low reverse current < 1 nA typ.
- Very low series inductance down to 0.2 nH typ.
- Low capacitance of 4 pF typ.
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101

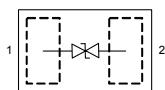
Applications

- USB 2.0, 10/100 Ethernet, Firewire, DVI
- Mobile communication
- Consumer products (STB, MP3, DVD, DSC...)
- LCD displays, camera
- Notebooks and desktop computers, peripherals



ESD8V0R1B-02LS

ESD8V0R1B-02LRH



Type	Package	Configuration	Marking
ESD8V0R1B-02LRH	TSLP-2-17	1 line, bi-directional	E
ESD8V0R1B-02LS	TSSLP-2-1	1 line, bi-directional	E

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value		Unit
ESD discharge ¹⁾	V_{ESD}			kV
air		18		
contact		15		
Peak pulse current ($t_p = 8 / 20 \mu\text{s}$) ²⁾	I_{pp}	1		A
Operating temperature range	T_{op}	-55...150		°C
Storage temperature	T_{stg}	-65...150		

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

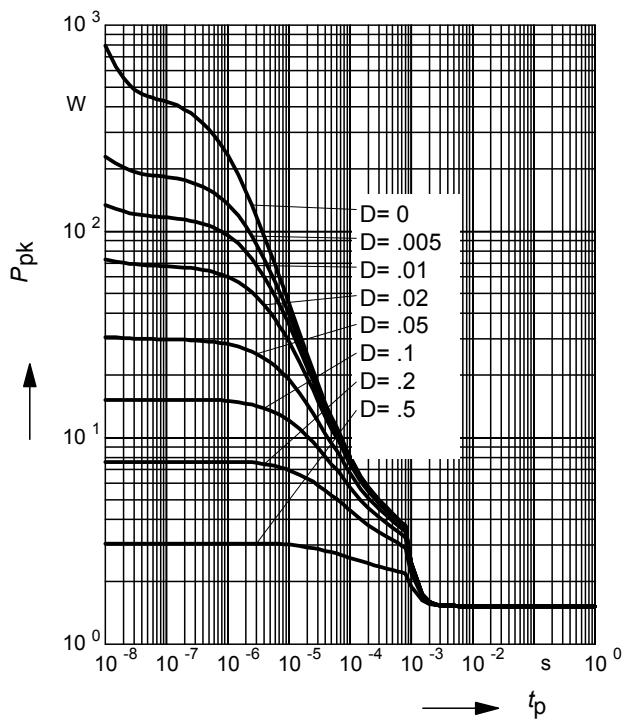
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Reverse working voltage, from pin 2 to 1	V_{RWM}	-8	-	14	V
Breakdown voltage $I_{(\text{BR})} = 1 \text{ mA}$, from pin 2 to 1 $I_{(\text{BR})} = 1 \text{ mA}$, from pin 1 to 2	$V_{(\text{BR})}$	14.5 8.5	17 11	20 14	
Reverse current $V_R = 3.3 \text{ V}$	I_R	-	<1	50	nA
Clamping voltage $I_{\text{PP}} = 1 \text{ A}$, $t_p = 8/20 \mu\text{s}$, from pin 2 to 1 ²⁾ $I_{\text{PP}} = 1 \text{ A}$, $t_p = 8/20 \mu\text{s}$, from pin 1 to 2 ²⁾	V_{CL}	- -	23 17	28 22	V
Line capacitance $V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$	C_T	-	4	7	pF
Series inductance ESD8V0R1B-02LS ESD8V0R1B-02LRH	L_S	- -	0.2 0.4	- -	nH

¹ V_{ESD} according to IEC61000-4-2

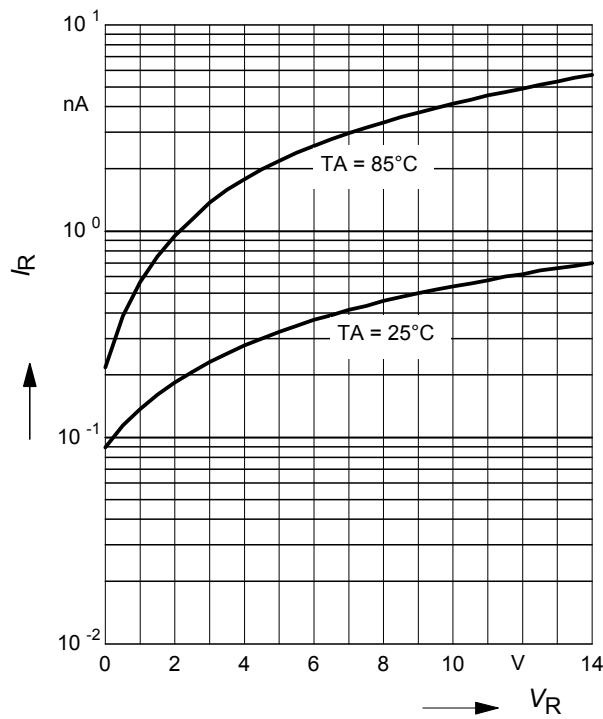
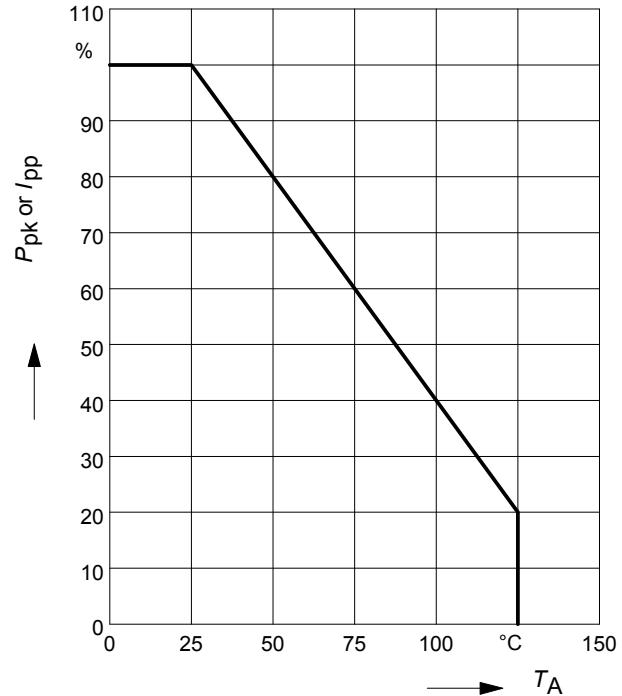
² I_{pp} according to IEC61000-4-5

Non-repetitive peak pulse power

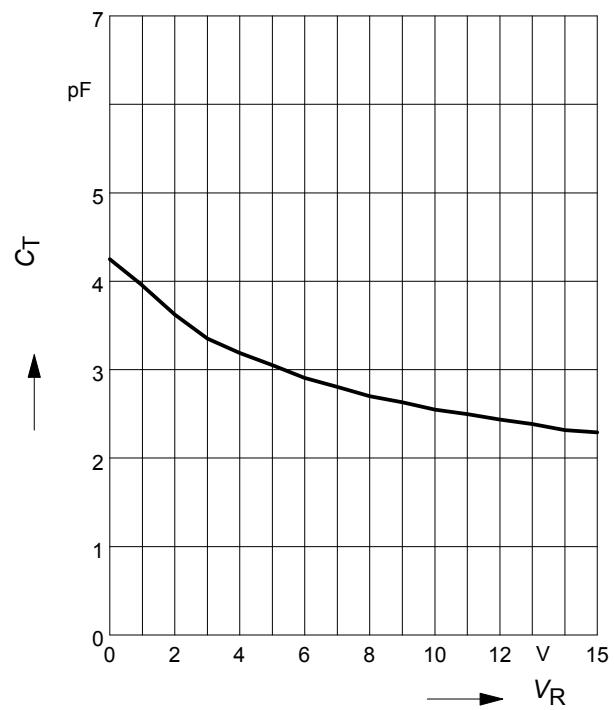
$$P_{pk} = f(t_p)$$



Reverse current $I_R = f(V_R)$

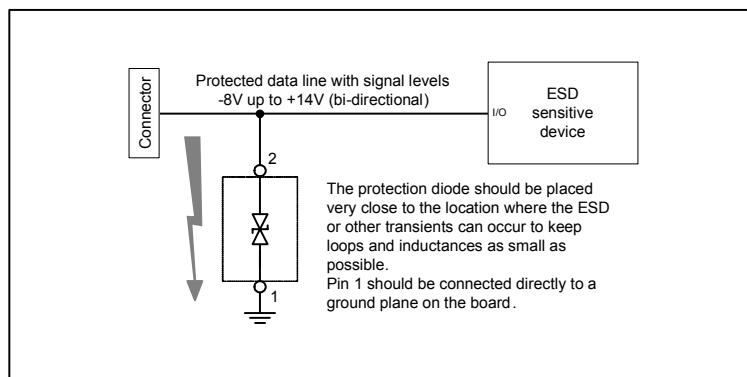
 T_A = Parameter

Power derating curve $P_{pk} = f(T_A)$


Diode capacitance $C_T = f(V_R)$

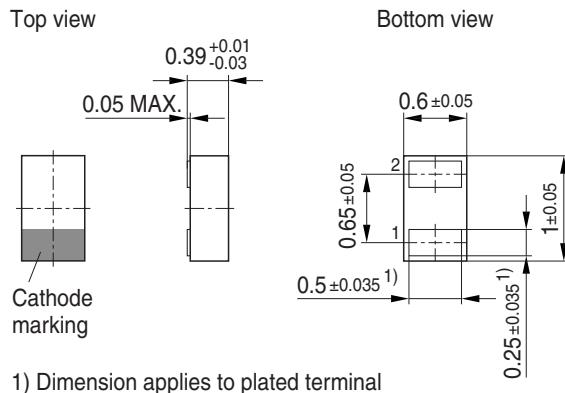
 $f = 1\text{MHz}$


Application example ESD8V0R1B...

1 line, bi-directional

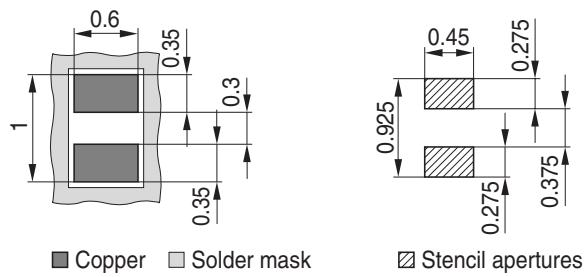


Package Outline

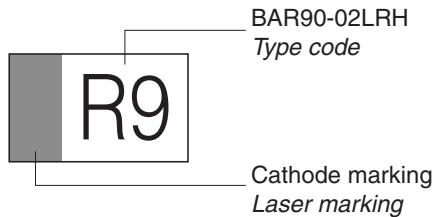


Foot Print

For board assembly information please refer to Infineon website "Packages"



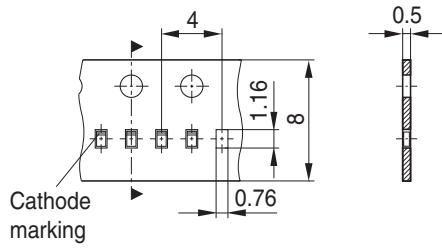
Marking Layout (Example)



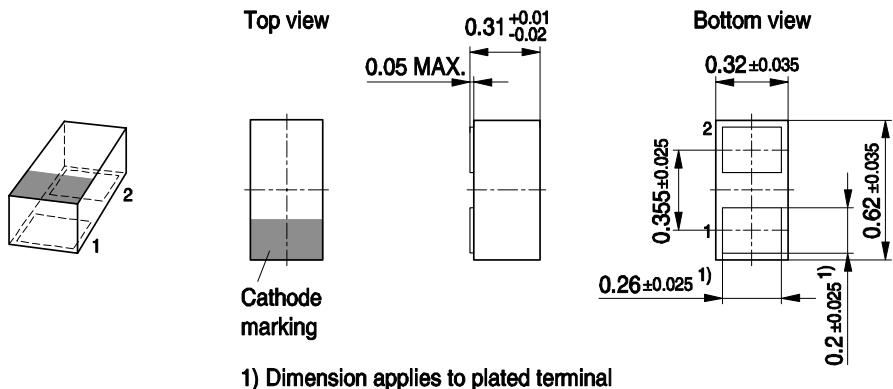
Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel

Reel ø330 mm = 50.000 Pieces/Reel (optional)

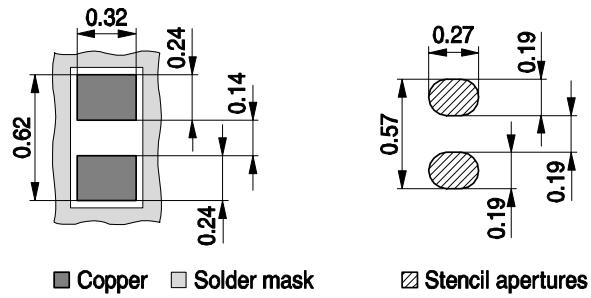


Package Outline

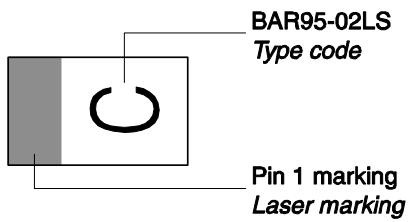


Foot Print

For board assembly information please refer to Infineon website "Packages"

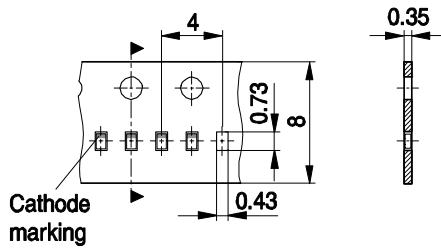


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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